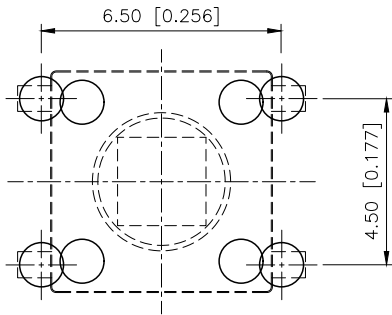
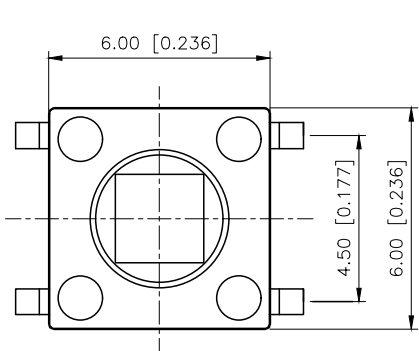
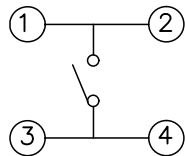


REVISIONS					
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A0	N/A		INITIAL RELEASE	/	/
A1	N/A		图面升级整理图面	2025.05.26	阿树



P.C.B MOUNTING PATTERN DIMENSION
The following sildering patterns are
recommended for reflow soldering

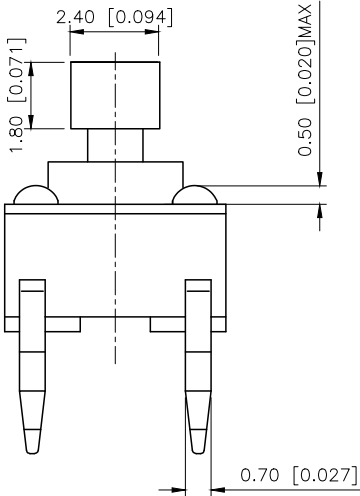
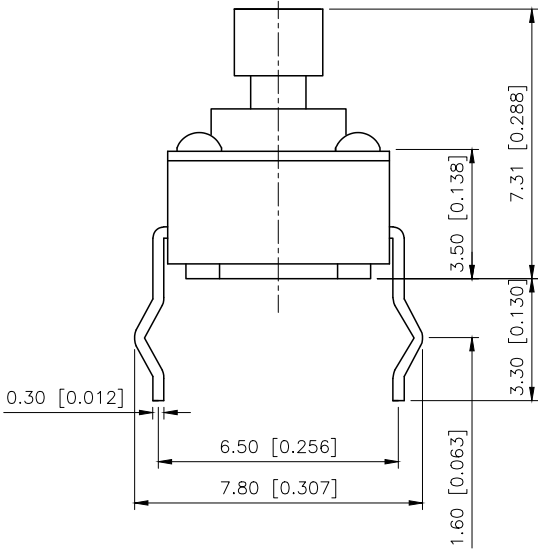


CIRCUIT DIAGRAM

SPECIFICATION
Contact Rating: 50mA,12V DC
Contact Resistance: 100mΩ max
Insulation Resistance: 100MΩ min.500V DC
Dielectric Strength: 250V AC/1minute
Travel: 0.25mm
Operating Temp: -30℃~+85℃
Storage Temp: -30℃~+80℃

PAPT NO	TC-1102T-X
Operating Force	A:100gf B:160gf C:260gf
Height	H:7.3

⑤	Terminal	4	Brass (0.30t)	Plating silvering
④	Contact	1	F.ag/SUS	Natural
③	Base	1	PA46	
②	Cover	1	Spcc	Plating Nickel
①	Keystake	1	PA46	
ITEM	PAPT NAMF	QTY	MATERIAL	FINISHING



AuGLAR	±5°
X.	±0.40
X.x	±0.30
X.xx	±0.20
X.xxx	±0.15
UNSPECIFIED TOLERAUCES	



DESIGN	阿树	VIEW:		MODEL TYPE:	TACT SWITCH
CHECKED		UNIT:	mm/in	PART NO.:	TC-1102T-X
APPROVED		SIZE:	A4	DWG NO.:	